

a common signal line coupled to said first die, said common signal line being adapted to apply a signal in common to a plurality of second dice on a wafer; and

a temporary isolation device provided between said common signal line and said first die, said temporary isolation device being adapted to selectively connect and disconnect said first die from said common signal line.

26 *25*
43. (New) An apparatus of claim *42* wherein said temporary isolation device is a unidirectional current device.

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Cont.

27 *26*
44. (New) An apparatus of claim *43* wherein said temporary isolation device is a diode.

28 *26*
45. (New) An apparatus of claim *43* wherein said temporary isolation device is a transistor.

29 *28*
46. (New) An apparatus of claim *45* wherein said transistor is connected as a diode.

30
~~47~~ (New) An apparatus of claim ~~45~~ wherein said transistor is connected to be controlled by an applied signal.

31
~~48~~ (New) An apparatus of claim ~~42~~ wherein said common signal line supplies a power supply signal to said first die and said second dice.

A1
Cont.
32
~~49~~ (New) An apparatus of claim ~~42~~ wherein said common signal line is provided on said wafer.

33
~~50~~ (New) An apparatus of claim ~~42~~ further comprising an external interface for testing said first die and wherein said common signal line is coupled to said external interface.

34
~~51~~ (New) An apparatus of claim ~~50~~ wherein said temporary isolation device is provided at an external interface for testing said first die.

35 *33*
52. (New) An apparatus of claim *50* further comprising a permanent isolation device provided in series with said temporary isolation device, said permanent isolation device adapted to allow permanent isolation between said common signal line and said first die.

36 *35*
53. (New) An apparatus of claim *52*, wherein said permanent isolation device is provided at an external interface for testing said plurality of dies.

A 1
Cont. *37* *25*
54. (New) An apparatus of claim *42* wherein said temporary isolation device is provided on said wafer adjacent to said die.

38 *25*
55. (New) An apparatus of claim *42* wherein said temporary isolation device is provided on said wafer.

39 *25*
56. (New) An apparatus of claim *42* wherein said temporary isolation device is provided in a street area of said wafer.

40 *25*
57. (New) An apparatus of claim *42* wherein said temporary isolation device is provided on said first die.

41 *25*
58. (New) An apparatus of claim *42*, further comprising a permanent isolation device provided in series with said temporary isolation device, said permanent isolation device being adapted to selectively allow for permanent isolation of said common signal line from said first die.

42 *41*
59. (New) An apparatus of claim *58*, wherein said permanent isolation device comprises a fuse.

43 *41*
60. (New) An apparatus of claim *58*, wherein said permanent isolation device is provided off said first die.

44 *41*
61. (New) An apparatus of claim *58*, wherein said permanent isolation device is provided in a street area of said wafer.

45 25
52. (New) An apparatus of claim 42 further comprising a pair of shortable spaced terminals in an electrical path between said first die and said common signal line.

46 45
53. (New) An apparatus of claim 52 wherein a first one of said spaced terminals is provided on said first die and a second one of said terminals is provided off said first die.

A'

47 46
54. (New) An apparatus of claim 53 wherein said second one of said terminals is provided in a street area of said wafer.